

# SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS398G – APRIL 1998 – REVISED APRIL 2005

- 2-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 7 ns at 5 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  
<0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  
>2.3 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

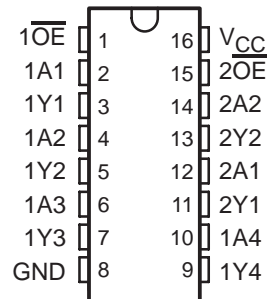
## description/ordering information

The 'LV367A devices are hex buffers and line drivers designed for 2-V to 5.5-V  $V_{CC}$  operation. These devices are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

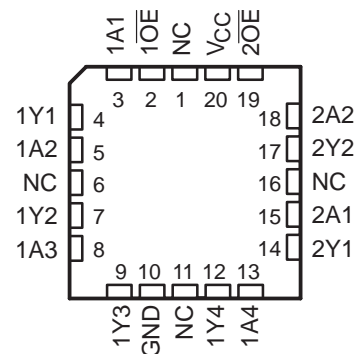
The 'LV367A devices are organized as dual 4-line and 2-line buffers/drivers with active-low output-enable ( $\overline{1OE}$  and  $\overline{2OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes noninverted data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54LV367A . . . J OR W PACKAGE  
SN74LV367A . . . D, DB, DGV, NS, OR PW PACKAGE  
(TOP VIEW)



SN54LV367A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – D	Tube of 40	SN74LV367AD	LV367A
		Reel of 2500	SN74LV367ADR	
	SOP – NS	Reel of 2000	SN74LV367ANSR	74LV367A
	SSOP – DB	Reel of 2000	SN74LV367ADBR	LV36A
	TSSOP – PW	Reel of 2000	SN74LV367APWR	LV367A
		Reel of 250	SN74LV367APWT	
–55°C to 125°C	TVSOP – DGV	Reel of 2000	SN74LV367ADGVR	LV367A
	CDIP – J	Tube of 25	SNJ54LV367AJ	SNJ54LV367AJ
	CFP – W	Tube of 150	SNJ54LV367AW	SNJ54LV367AW
	LCCC – FK	Tube of 55	SNJ54LV367AFK	SNJ54LV367AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

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# SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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FUNCTION TABLE  
(each buffer/driver)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

## logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1)	-0.5 V to 7 V
Output voltage range applied in the high or low state, $V_O$ (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	
D package	73°C/W
DB package	82°C/W
DGV package	120°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  2. This value is limited to 5.5 V maximum.
  3. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 4)

		SN54LV367A		SN74LV367A		UNIT	
		MIN	MAX	MIN	MAX		
V <sub>CC</sub>	Supply voltage	2	5.5	2	5.5	V	
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	1.5		V	
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7	V <sub>CC</sub> × 0.7			
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7	V <sub>CC</sub> × 0.7			
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7	V <sub>CC</sub> × 0.7			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	0.5		V	
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3			
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3			
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3			
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V	
V <sub>O</sub>	Output voltage	High or low state	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
		3-state	0	5.5	0	5.5	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V		-50	-50	μA	
		V <sub>CC</sub> = 2.3 V to 2.7 V		-2	-2	mA	
		V <sub>CC</sub> = 3 V to 3.6 V		-8	-8		
		V <sub>CC</sub> = 4.5 V to 5.5 V		-16	-16		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V		50	50	μA	
		V <sub>CC</sub> = 2.3 V to 2.7 V		2	2	mA	
		V <sub>CC</sub> = 3 V to 3.6 V		8	8		
		V <sub>CC</sub> = 4.5 V to 5.5 V		16	16		
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V		200	200	ns/V	
		V <sub>CC</sub> = 3 V to 3.6 V		100	100		
		V <sub>CC</sub> = 4.5 V to 5.5 V		20	20		
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LV367A			SN74LV367A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1			V <sub>CC</sub> -0.1			V
	I <sub>OH</sub> = -2 mA	2.3 V	2			2			
	I <sub>OH</sub> = -8 mA	3 V	2.48			2.48			
	I <sub>OH</sub> = -16 mA	4.5 V	3.8			3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V to 5.5 V				0.1			V
	I <sub>OL</sub> = 2 mA	2.3 V				0.4			
	I <sub>OL</sub> = 8 mA	3 V				0.44			
	I <sub>OL</sub> = 16 mA	4.5 V				0.55			
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V				±1			μA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V				±5			μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V				20			μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0				5			μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	3			3			pF
C <sub>o</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5.2			5.2			pF

switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54LV367A		SN74LV367A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 15 pF	6.4*	12.7*		1*	16*	1	16	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y		6.9*	14.9*		1*	20*	1	20	
t <sub>dis</sub>	$\overline{\text{OE}}$	Y		6.4*	14.9*		1*	20*	1	20	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 50 pF	8.6	17.5		1	21	1	21	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y		9.4	19.7		1	25	1	25	
t <sub>dis</sub>	$\overline{\text{OE}}$	Y		10.1	19.7		1	25	1	25	
t <sub>sk(o)</sub>							2			2	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54LV367A		SN74LV367A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 15 pF	4.7*	8.3*		1*	10*	1	10	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y		5.1*	10.5*		1*	12.5*	1	12.5	
t <sub>dis</sub>	$\overline{\text{OE}}$	Y		4.9*	10.5*		1*	12.5*	1	12.5	
t <sub>pd</sub>	A	Y	C <sub>L</sub> = 50 pF	6.2	11.8		1	13.5	1	13.5	ns
t <sub>en</sub>	$\overline{\text{OE}}$	Y		6.8	14		1	16	1	16	
t <sub>dis</sub>	$\overline{\text{OE}}$	Y		7.3	13.6		1	15.5	1	15.5	
t <sub>sk(o)</sub>							1.5			1.5	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV367A		SN74LV367A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	$C_L = 15\text{ pF}$	3.6*	5.9*	1*	7*	1	7	ns	
$t_{en}$	$\overline{OE}$	Y		3.8*	7.2*	1*	8.5*	1	8.5		
$t_{dis}$	$\overline{OE}$	Y		2.6*	7.2*	1*	8.5*	0	8.5		
$t_{pd}$	A	Y	$C_L = 50\text{ pF}$	4.5	7.9	1	9	1	9	ns	
$t_{en}$	$\overline{OE}$	Y		4.9	9.2	1	10.5	1	10.5		
$t_{dis}$	$\overline{OE}$	Y		4.5	9.2	1	10.5	0	10.5		
$t_{sk(o)}$						1			1		

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics,  $V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 5)

PARAMETER		SN74LV367A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$	0.5	0.8		V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$	-0.2	-0.8		V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$	3			V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage		0.99		V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 10\text{ MHz}$	3.3 V	14.9	pF
			5 V	17.4	

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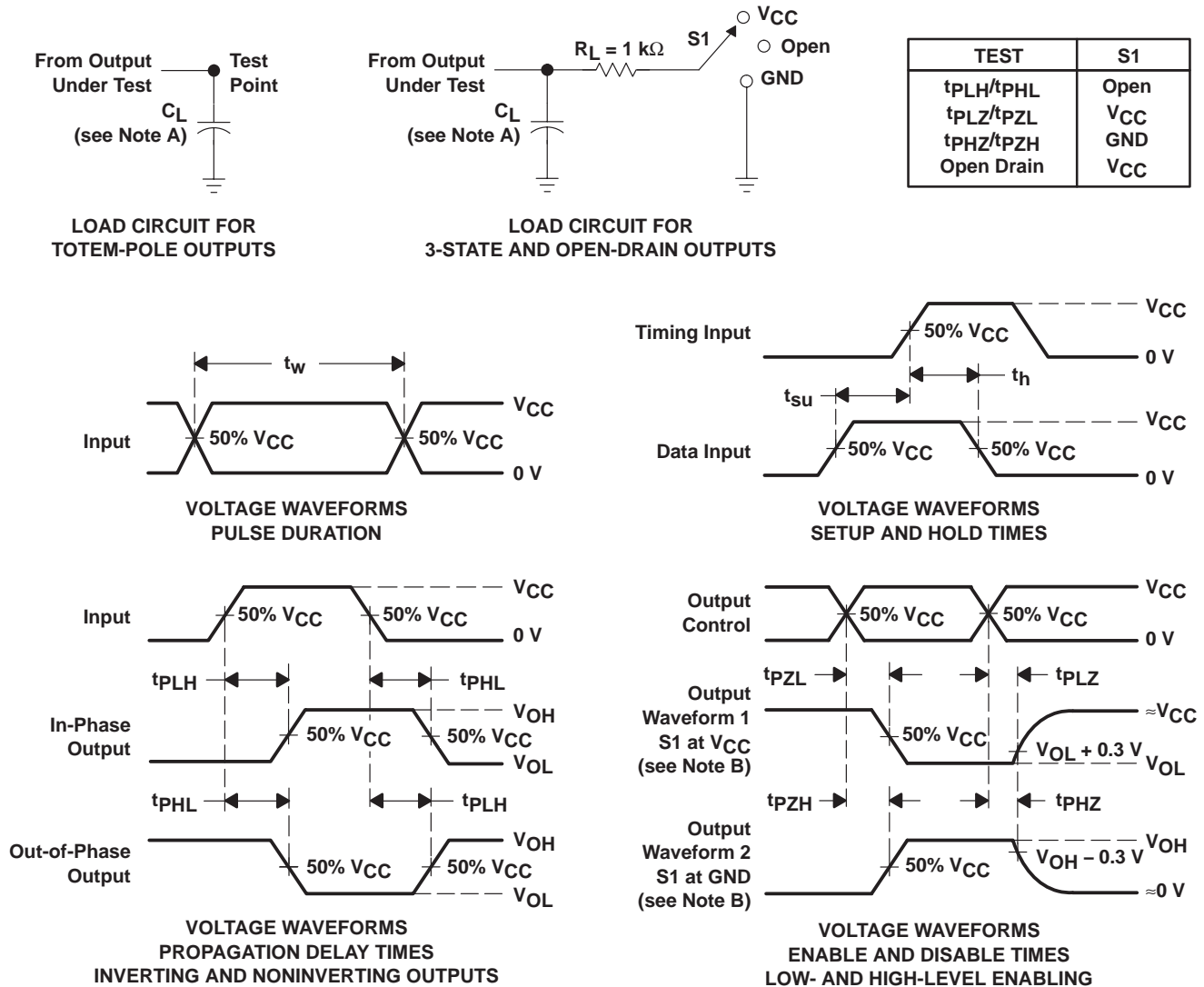


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## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV367AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADGVRG4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367APWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV367AQPWRQ1	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV367ADBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV367ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV367ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV367ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV367APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV367APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV367ADBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74LV367ADGVR	TVSOP	DGV	16	2000	367.0	367.0	35.0
SN74LV367ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV367ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LV367APWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV367APWT	TSSOP	PW	16	250	367.0	367.0	35.0

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

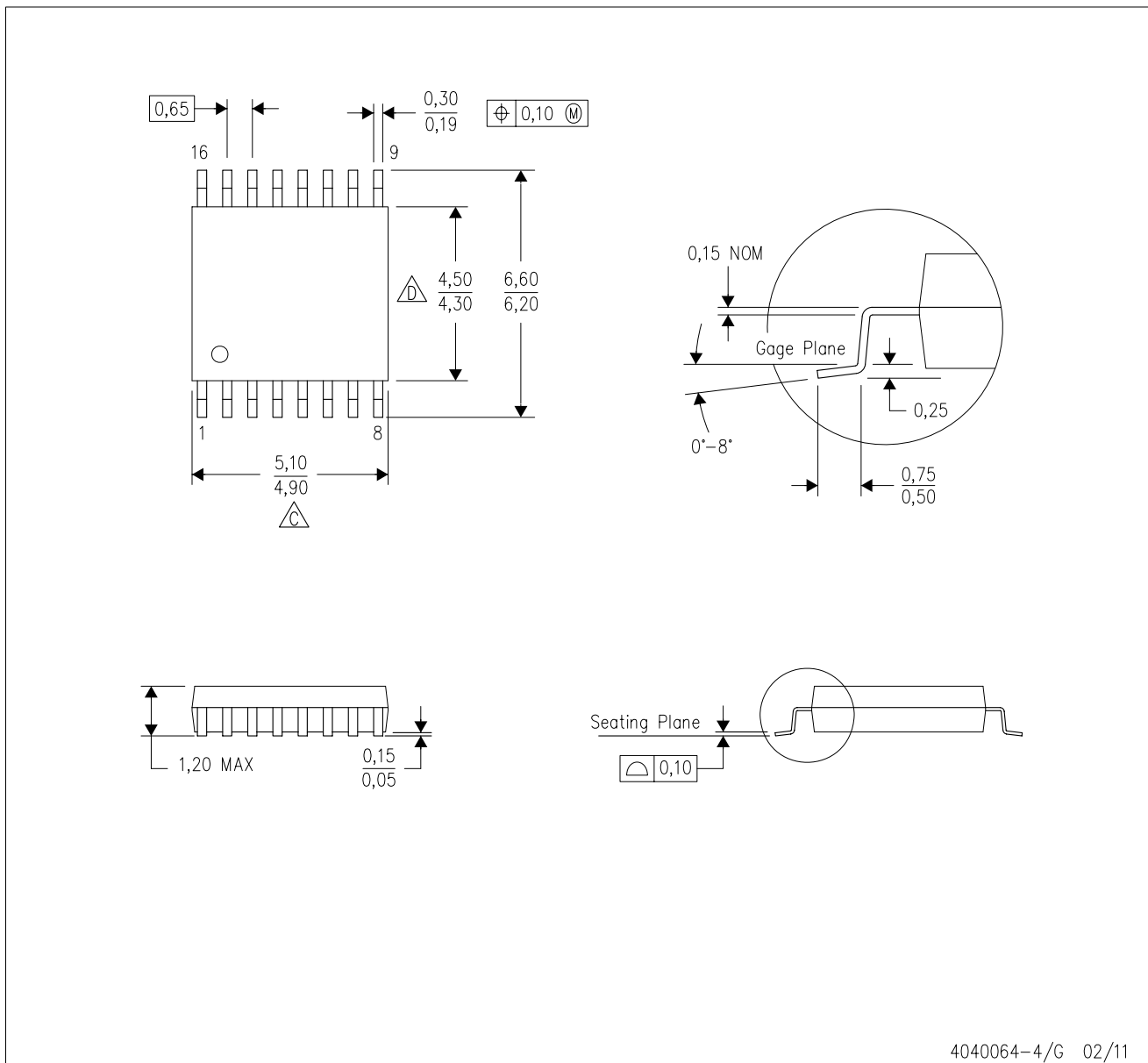
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

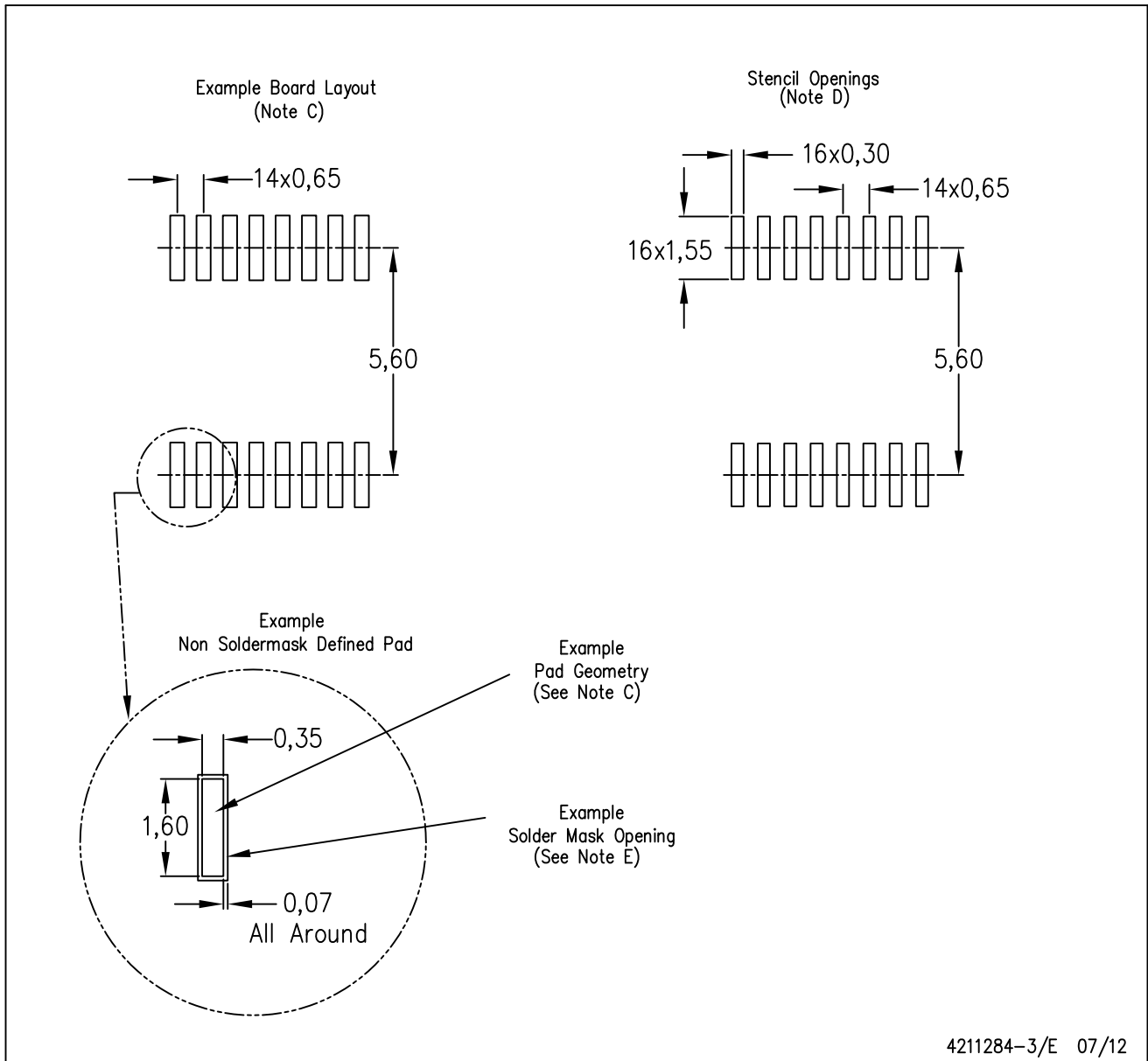


4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/E 07/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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